Materials Declaration

Package	LFCSP
Body Size	5 X 5
LeadCount	28
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Resin	10	2.47 E-03	41143
SiO2 Filler	85	2.10 E-02	349712
Phenol Resin	5	1.24 E-03	20571

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.94 E-02	489964
Fe	2.35	7.10 E-04	11809
P	0.03	9.06 E-06	151
Zn	0.12	3.62 E-05	603

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.80 E-04	9651

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.38 E-04	3966

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-03	16655

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	2.87 E-03	47676

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.22 E-04	2025
Ag Filler	75	3.65 E-04	6074

Package Totals

Weight (g)	PPM
6.01 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	4	EPA3050B (ICPAES)
Cd	<2	BSEN 1122:2001B (ICP AES)
Hg	<2	Mercury Analyser
Cr+6	<2	EPA3060A (UV)

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	Not Detected	ICP AES

AMK-CP-C

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ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

Materials Declaration

Package	LFCSP
Body Size	5 X 5
LeadCount	28
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Resin	10	2.47 E-03	41143
SiO2 Filler	85	2.10 E-02	349712
Phenol Resin	5	1.24 E-03	20571

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.94 E-02	489964
Fe	2.35	7.10 E-04	11809
P	0.03	9.06 E-06	151
Zn	0.12	3.62 E-05	603

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.80 E-04	9651

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.03 E-04	3371
Pb	15	3.58 E-05	595

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-03	16655

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	2.87 E-03	47676

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.22 E-04	2025
Ag Filler	75	3.65 E-04	6074

Package Totals

Weight (g)	PPM
6.01 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	4	EPA3050B (ICPAES)
Cd	<2	BSEN 1122:2001B (ICP AES)
Hg	<2	Mercury Analyser
Cr+6	<2	EPA3060A (UV)

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	Not Detected	ICP AES

AMK-CP-A

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